



## IC Knowledge – MEMS Cost Model Supported MEMS Processes List

As of December 11, 2008 the following MEMS processes are included in the MEMS Cost Model. Where “Enter Steps” is displayed the user may create their own process by filling in a table for the number of times each different standard process step is used in the process flow. The model now supports multiple MEMS die per product and “none” is used to turn off individual die.

1. None
2. Enter steps
3. 2 Layer Poly
4. Bulk Pressure Sensor
5. Cap wafer
6. Coventor - RF Relay
7. Discera - MEMS Oscillator with cap
8. Electrosatic Motor
9. Floating Element Flow Sensor
10. HP - Print Head
11. IMEPKU - 2 layer poly
12. Infineon - Bulk Accoustic Wave
13. Infineon - Tire Pressure Measurement
14. Infotonics - Hybrid SOI
15. Invensense - Accelerometer (includes ASIC cavity formation)
16. Knowles - Microphone
17. Lear - Tire Pressure Sensor
18. MEMSCap - Metal MUMPS
19. MEMSCap - Poly MUMPS
20. MEMSCap - SOI MUMPS
21. Protein Sensor
22. RF Relay
23. Robert Bosch - Accelerometer
24. SiTime - Oscillator
25. STMicro - Thelma
26. SUMMiT - 3 poly layers